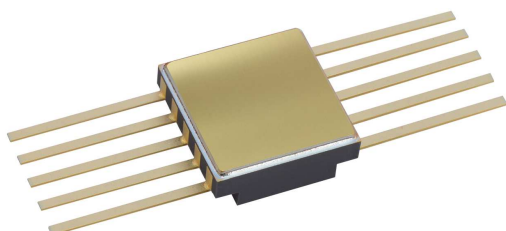


Rad-hard adjustable 2.5 V/5.5 V precision shunt V-ref

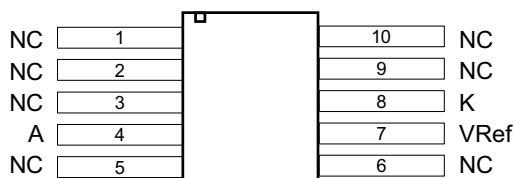
Datasheet - production data



Ceramic Flat-10

The upper metallic lid is not electrically connected to any pins, nor to the IC die inside the package

Pin connections
(top view)



Applications

- Space systems
- Space data acquisition systems
- Aerospace instrumentation
- ADC references

Description

The RHF1009A is a low-power adjustable 2.5 V voltage reference, specifically designed to sustain radiations in space applications.

Mounted in a Flat-10 ceramic package, the RHF1009A uses a dedicated architecture and design rules to provide the best immunity against heavy-ions.

A very low operating current and very good stability over a wide temperature range of -55 °C to +125 °C make the RHF1009A particularly suitable for precision and power saving.

Features

- Adjustable shunt, 2.5 V to 5.5 V
- High precision $\pm 0.2\%$ at 2.5 V at 25 °C
- Wide operating current: 60 μ A to 12 mA
- 30 ppm/°C maximum temperature range at 2.5 V
- Stable on capacitive load
- ELDRS-free up to 300 krad
- 300 krad high/low dose rate
- SEL-free up to 120 MeV.cm²/mg
- SET characterized
- Mass = 0.50 g
- SMD: 5962F14222

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1 Absolute maximum ratings and operating conditions

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
I_K	Reverse breakdown current	15	mA
I_F	Forward current	20	mA
V_{KA}	Reverse breakdown voltage in standby mode ($V_{Ref} = V_A$)	6	V
T_{stg}	Storage temperature	-65 to +150	°C
T_j	Maximum junction temperature	150	°C
R_{thja}	Thermal resistance junction (T_j) to ambient (T_{amb})	140	°C/W
R_{thjc}	Thermal resistance junction to case	40	°C/W
ESD	HBM: human body model ⁽¹⁾	2	kV
	MM: machine model ⁽²⁾	200	V
	CDM: charged device model ⁽³⁾	1.5	kV

- Human body model: a 100 pF capacitor is charged to the specified voltage, then discharged through a 1.5 kΩ resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are left floating.
- This is a minimum value.
Machine model: a 200 pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 Ω). This is done for all couples of connected pin combinations while the other pins are left floating.
- Charged device model: all pins and package are charged together to the specified voltage and then discharged directly to ground through only one pin.

Table 2. Operating conditions

Symbol	Parameter	Value	Unit
I_{Kmin}	Minimum operating current [$V_K \geq V_K (I_K = 100 \mu A, T_a = 25^\circ C) - 100 \mu V$ $V_K = V_{Ref}$]	60	μA
V_{KA}	Reverse breakdown voltage in operating mode: in standby mode ($V_{Ref} = V_A$):	2.5 to 5.5 2.5 to 5.5	V
I_{Kmax}	Maximum operating current [$V_K \geq V_K (I_K = 100 \mu A, T_a = 25^\circ C) + 2 mV$ $V_K = V_{Ref}$]	12	mA
T_{oper}	Operating ambient temperature range	-55 to +125	°C

2 Electrical characteristics

Parameters tested before radiation are shown in [Table 3](#).

Table 3. Anode is connected to Gnd (0 V), V_K is in reference to anode voltage. C_K (between anode and cathode) = 100 nF, $R_1 = 0$ and R_2 not connected unless otherwise specified

Symbol	Parameter	Test conditions	Temp.	Min.	Typ.	Max.	Unit
DC performance							
V_{Ref}	Reference input voltage	$I_K = 100 \mu A$ $V_K = V_{Ref}$	+25 °C		2.5		V
ΔV_{Ref}	Reference input voltage tolerance	$I_K = 100 \mu A$ $V_K = V_{Ref}$	+25 °C	-5		+5	mV
I_{Kmin}	Minimum operating current	$[V_K \geq V_K (I_K = 100 \mu A,$ $T_a = 25^\circ C) - 100 \mu V]$ $V_K = V_{Ref}$	-55 °C +25 °C +125 °C			60 60 60	μA
I_{Koff}	Off state cathode current	$V_{Ref} = V_A$ $V_{KA} = 2.5V$	-55 °C +25 °C +125 °C			1 1 1	μA
I_{Ref}	Reference input current	$I_K = 100 \mu A$ to 10 mA $V_K = V_{Ref}$ on $R_1 =$ 10 k Ω	-55 °C +25 °C +125 °C			1 1 1	μA
$\Delta V_{Ref}/\Delta T$	Average temperature coefficient $\frac{V_{Refmax} - V_{Refmin}}{180^\circ C \times V_{Ref}(25^\circ C)} \times 10^6$	$I_K = 100 \mu A$ $V_K = V_{Ref}$	-55 °C to +125 °C			30	ppm/ °C
		$I_K = 10 mA$ $V_K = V_{Ref}$	-55 °C to +125 °C			30	
$\Delta V_{Ref}/\Delta V_{KA}$	Reference voltage versus cathode voltage variation	$I_K = 100 \mu A$ $V_{KA} = 2.5 V$ to 5.5 V $R_1 = 10 k\Omega$, R_2 Variable	-55 °C to +125 °C		1.5	2.5	mV/V
		$I_K = 10 mA$ $V_{KA} = 2.5 V$ to 5.5 V $R_1 = 10 k\Omega$, R_2 Variable	-55 °C to +125 °C		1.5	2.5	
$\Delta V_{Ref}/\Delta I_K$	Reference voltage versus cathode current variation	$I_{Kmin} \leq I_K \leq 1 mA$ $V_K = V_{Ref}$	-55 °C +25 °C +125 °C		0.075 0.08 0.15	0.15 0.16 0.3	mV
		$1 mA \leq I_K \leq 12 mA$ $V_K = V_{Ref}$	-55 °C +25 °C +125 °C		0.65 0.7 1	1.3 1.4 2	
R_{KA}	Reverse static impedance	$\Delta I_K = I_{Kmin}$ to 10 mA $V_K = V_{Ref}$	-55 °C +25 °C +125 °C		0.05 0.06 0.1	0.1 0.12 0.2	Ω
Z_{KA}	Reverse dynamic impedance	$I_K = 1 mA$ to 1.1 mA $V_K = V_{Ref}$, $F \leq 1 kHz$ No capacitive load	-55 °C +25 °C +125 °C		0.4 0.4 0.5		Ω

Table 3. Anode is connected to Gnd (0 V), V_K is in reference to anode voltage. C_K (between anode and cathode) = 100 nF, $R_1 = 0$ and R_2 not connected unless otherwise specified (continued)

Symbol	Parameter	Test conditions	Temp.	Min.	Typ.	Max.	Unit
$K_{vh}^{(1)}$	Long-term stability $\frac{ V_K(0hr) - V_K(1000hrs) }{V_K(0hr)} \times 10^6$	$I_K = 100 \mu A$ $V_K = V_{Ref}$ $t = 1000 \text{ hrs}$	-55 °C +25 °C +125 °C		100 100 100		ppm
K_{vhd}	Stability in radiation $\frac{ V_K(0rad) - V_K(300krad) }{V_K(0rad)} \times 10^6$	$I_K = 100 \mu A$ $V_K = V_{Ref}$ Total dose = 300 krad Dose rate = 0.01 rad/s	-55 °C +25 °C +125 °C		1000 1000 1000		ppm
en	Voltage noise	$I_K = 100 \mu A$ $V_K = V_{Ref}$ $F = 1 \text{ kHz}$	-55 °C +25 °C +125 °C		760 880 980		nV/ $\sqrt{\text{Hz}}$

1. Reliability verified with a cathode current setting $I_K = 10 \text{ mA}$

3 Radiation

Total ionizing dose (MIL-STD-883 TM 1019)

The products guaranteed for radiation within the RHA QML-V system fully comply with the MIL-STD-883 TM 1019 specification.

The RHF1009A is RHA QML-V, tested and characterized in full compliance with the MIL-STD-883 specification, both below 10 mrad/s and between 50 and 300 rad/s, as follows:

- All tests are performed in accordance with MIL-PRF-38535 and the test method 1019 of MIL-STD-883 for total ionizing dose (TID).
- The ELDRS characterization is performed in qualification only on both biased and unbiased parts, on a sample of ten units from two different wafer lots.
- Each wafer lot is tested at high-dose rate only, in the worst bias case condition, based on the results obtained during the initial qualification.

Heavy-ions

The behavior of the product when submitted to heavy-ions is not tested in production. Heavy-ion trials are performed on qualification lots only.

Table 4. Radiations

Type	Characteristics	Value	Unit
TID	180 krad/h high-dose rate (50 rad/s) up to:	300	krad
	ELDRS-free up to:	300	
	36 rad/h low-dose rate (0.01 rad/s) up to:	300	
Heavy-ions	SEL immunity up to: (at 125 °C, with a particle angle of 60 °)	120	MeV.cm²/mg
	SEL immunity up to: (at 125 °C, with a particle angle of 0 °)	60	
		SET (at 25 °C)	Characterized

Note: In Figure 1 to 24, temp. = temperature, freq. = frequency, and resp. = response.

Figure 1. Reverse breakdown voltage characteristics vs. cathode current

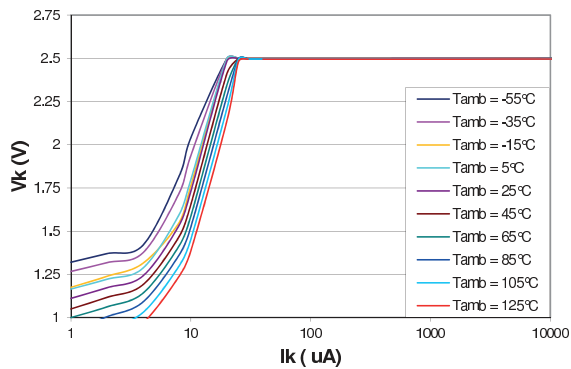


Figure 2. Zoom of reverse breakdown voltage characteristics vs. cathode current

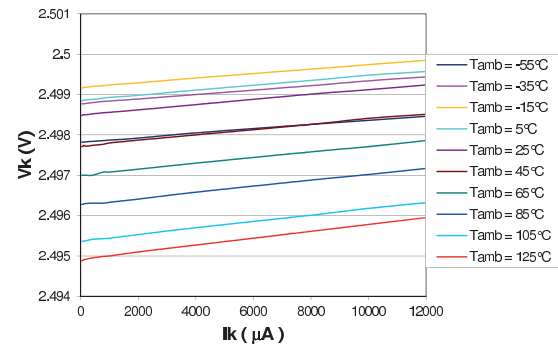


Figure 3. Reverse breakdown voltage characteristics vs. ambient temp.

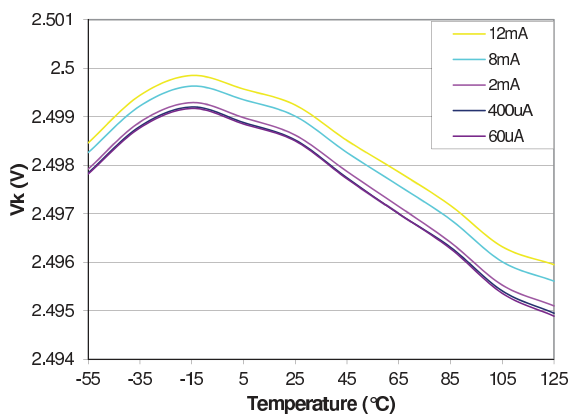


Figure 4. Average temp. coefficient vs. cathode current

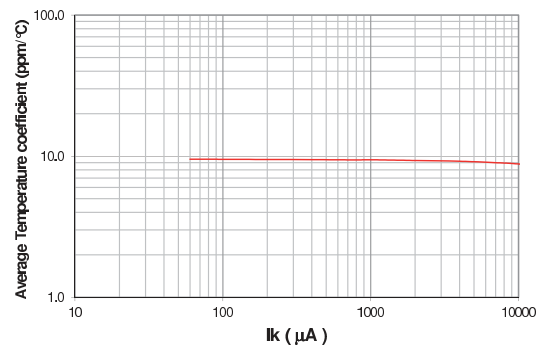


Figure 5. Output impedance vs. freq. at +125 °C, $C_k = 47$ nF

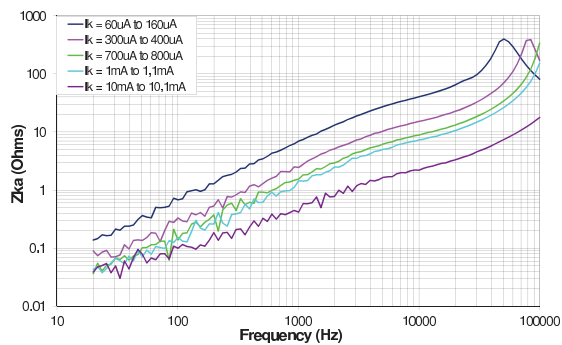
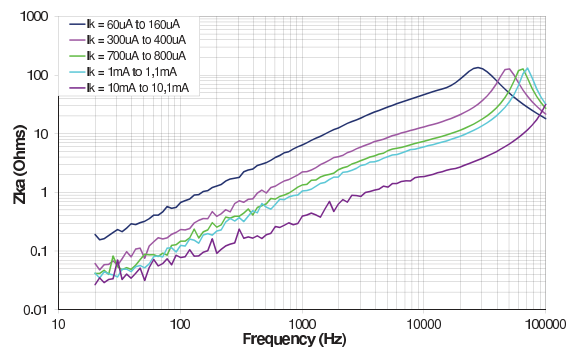
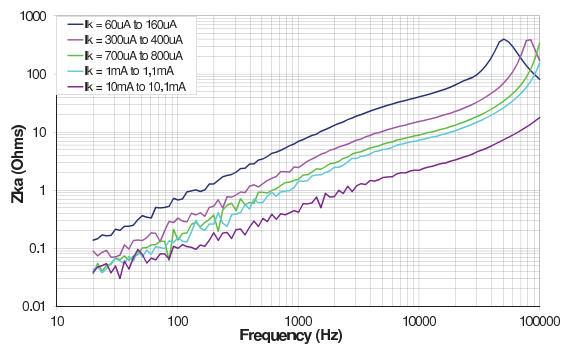


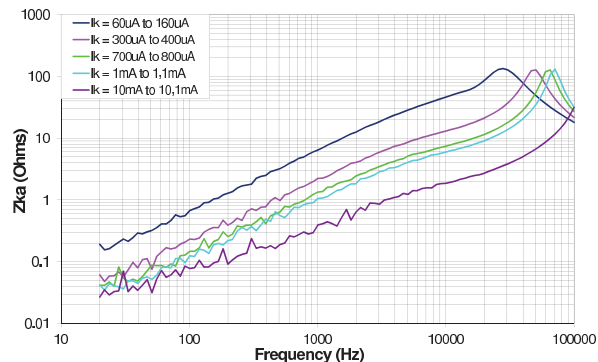
Figure 6. Output impedance vs. freq. at 125 °C, $C_k = 100$ nF



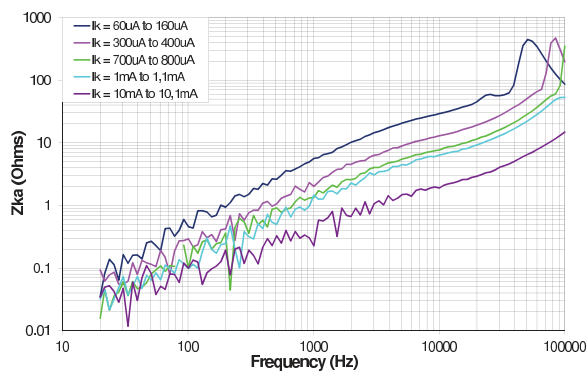
**Figure 7. Output impedance vs. freq. at +25 °C,
 $C_k = 47 \text{ nF}$**



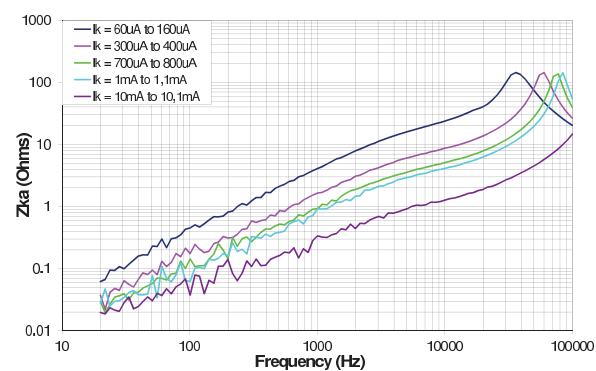
**Figure 8. Output impedance vs. freq. at 25 °C,
 $C_k = 100 \text{ nF}$**



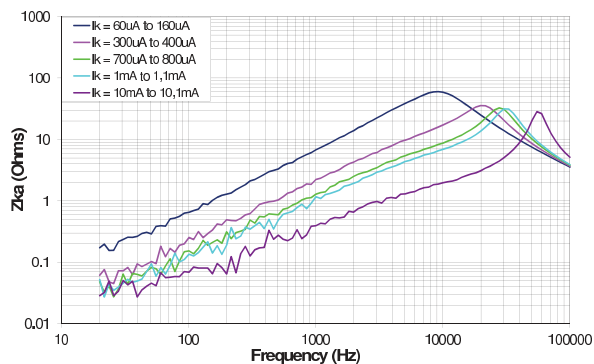
**Figure 9. Output impedance vs. freq. at -55 °C,
 $C_k = 47 \text{ nF}$**



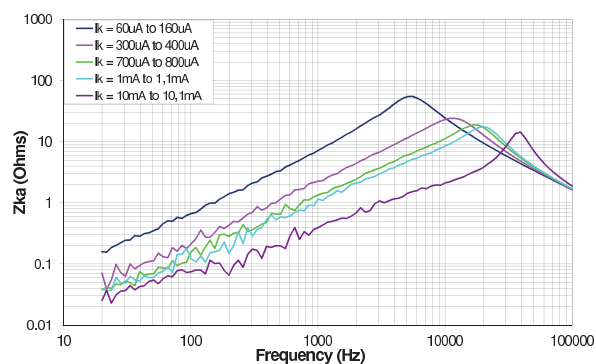
**Figure 10. Output impedance vs. freq. at -55 °C,
 $C_k = 100 \text{ nF}$**



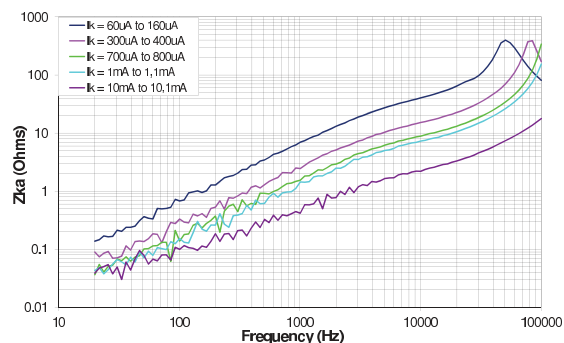
**Figure 11. Output impedance vs. freq. at
+125 °C, $C_k = 470 \text{ nF}$**



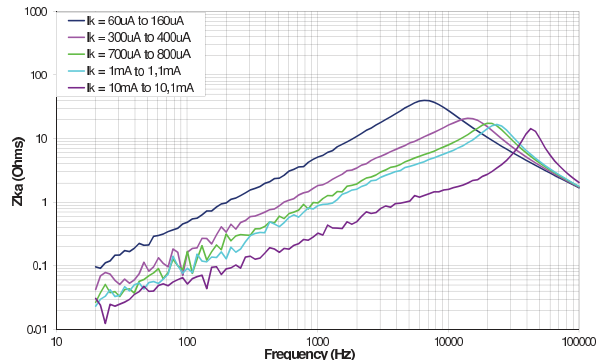
**Figure 12. Output impedance vs. freq. at
+125 °C, $C_k = 1 \mu\text{F}$**



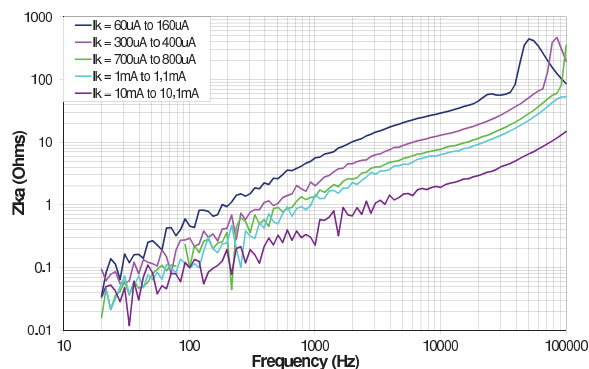
**Figure 13. Output impedance vs. freq. at +25 °C,
 $C_k = 470 \text{ nF}$**



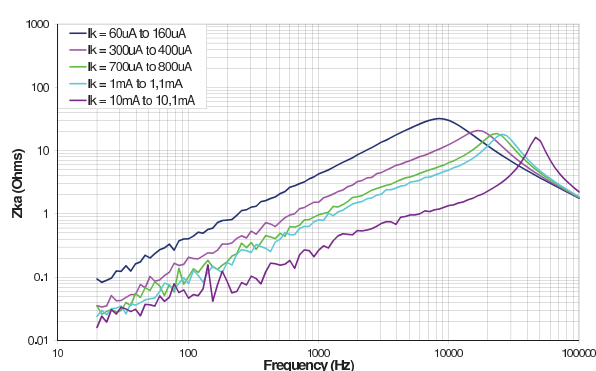
**Figure 14. Output impedance vs. freq. at +25 °C,
 $C_k = 1 \mu\text{F}$**



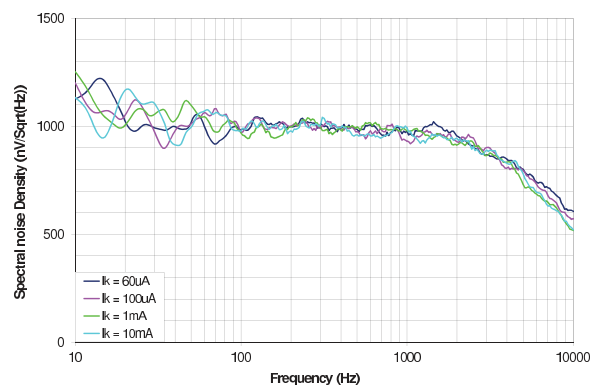
**Figure 15. Output impedance vs. freq. at -55 °C,
 $C_k = 470 \text{ nF}$**



**Figure 16. Output impedance vs. freq. at -55 °C,
 $C_k = 1 \mu\text{F}$**



**Figure 17. Spectral noise density vs. freq. at
+125 °C, $C_k = 100 \text{ nF}$**



**Figure 18. Spectral noise density vs. freq. at
+125 °C, $C_k = 1 \mu\text{F}$**

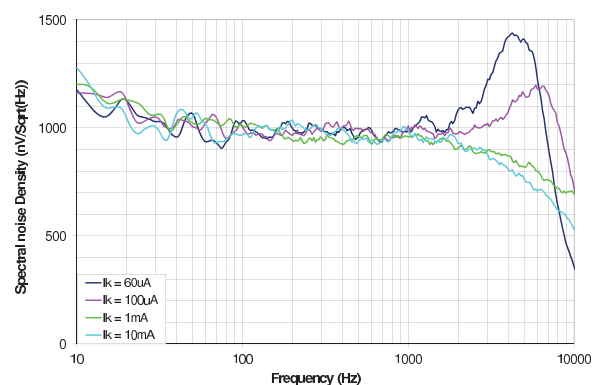


Figure 19. Spectral noise density vs. freq. at +25 °C, $C_k = 100$ nF

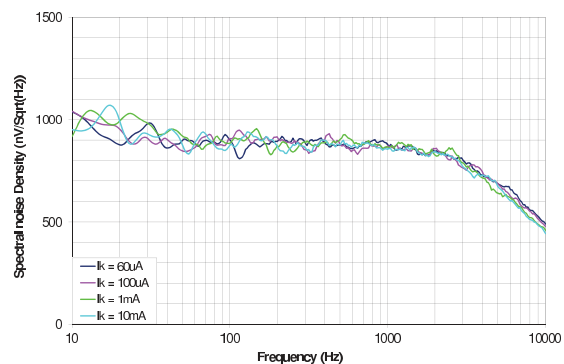


Figure 20. Spectral noise density vs. freq. at +25 °C, $C_k = 1$ μF

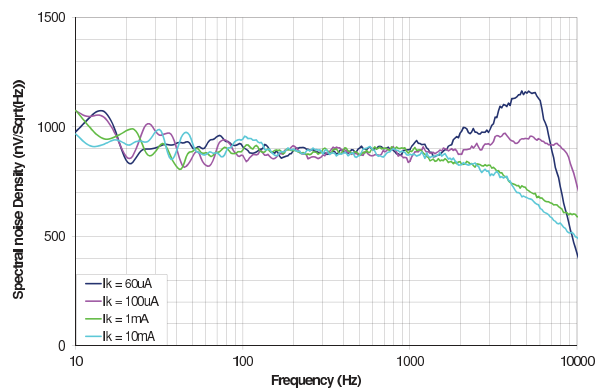


Figure 21. Spectral noise density vs. freq. at -55 °C, $C_k = 100$ nF

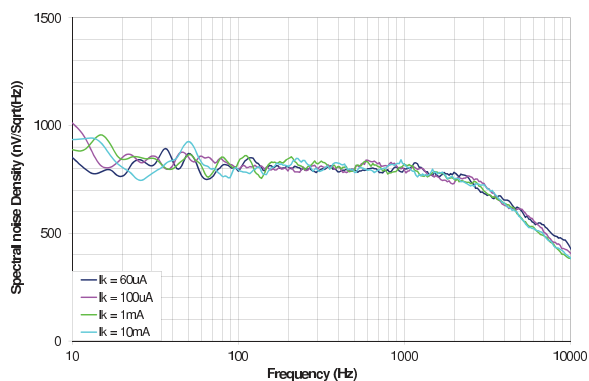


Figure 22. Spectral noise density vs. freq. at -55 °C, $C_k = 1$ μF

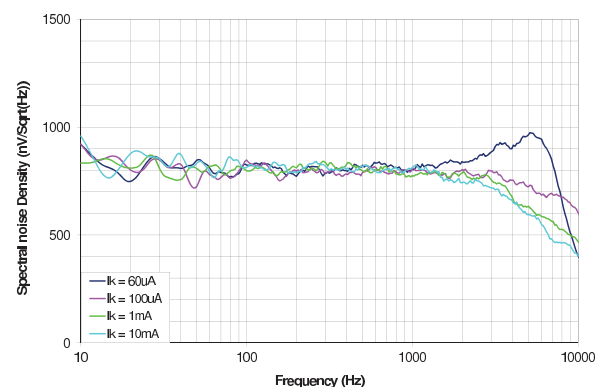


Figure 23. Low freq. spectral noise density vs. freq. $C_k = 100$ nF to 1 μF, $I_k = 60$ μA to 10 mA

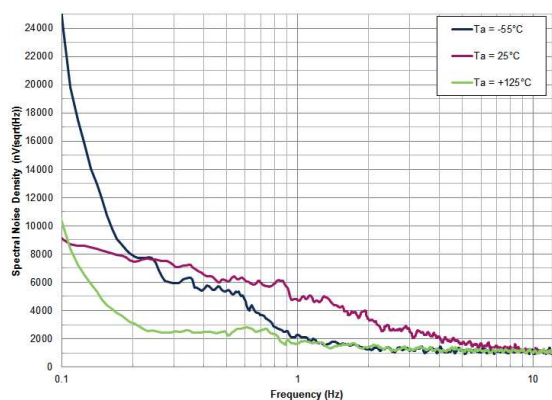
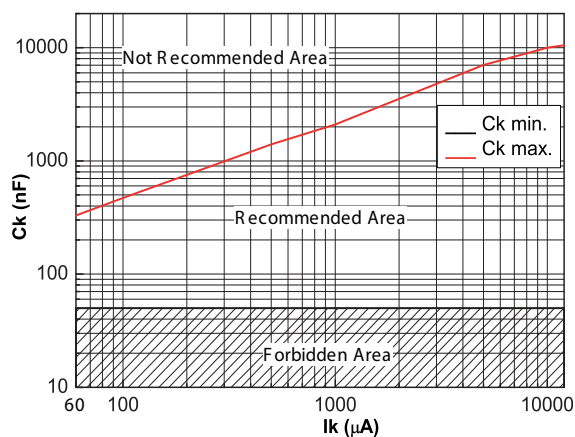


Figure 24. Recommended operating area



4 Design information

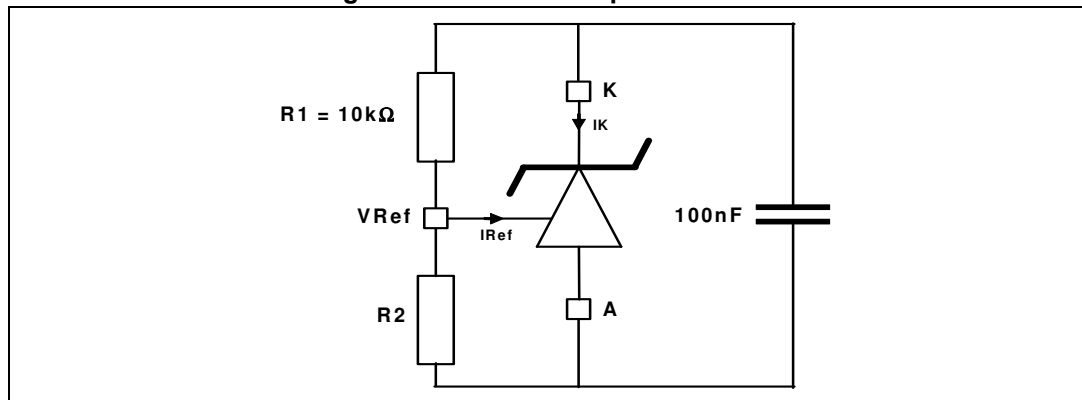
4.1 Introduction

The RHF1009A is a programmable voltage reference. It can be set from 2.5 V to 5.5 V by a bridge of 2 resistors (see [Figure 25](#)).

From -55 °C to +125 °C, the cathode current capability of the RHF1009A ranges from 60 µA up to 12 mA.

Internal double bonding allows the RHF1009A to have an equivalent output resistance as low as 110 mΩ. Consequently, the RHF1009A has very good load regulation.

Figure 25. Electrical implementation



$$V_{KA} = V_{Ref} \times \left(1 + \frac{R_1}{R_2}\right) + R_1 \times I_{Ref}$$

4.2 Average temperature coefficient

The RHF1009A is designed with a second order compensation in temperature. This gives an S-shaped curve for the V_k variation over the temperature range.

For the RHF1009A, the average temperature coefficient is calculated as shown in [Equation 1](#).

Equation 1

$$\text{Average temperature coefficient} = \frac{V_{kmax} - V_{kmin}}{(T_{max} - T_{min}) \times v_k(25^\circ\text{C})} \times 10^6$$

where $T_{max} = +125^\circ\text{C}$ and $T_{min} = -55^\circ\text{C}$.

For each sample, use [Equation 1](#) and the procedure below:

- Set a cathode current (I_k)
- Measure V_k at I_k with an ambient temperature of 25 °C
- Measure V_k at I_k with the following ambient temperatures: -55 °C, -15 °C, +75 °C, and +125 °C.
- For the above five temperature measurements, find the V_k maximum and minimum
- Apply [Equation 1](#)

The average temperature coefficient is evaluated during product qualification on the above five temperature measurements and is guaranteed on production tests with three temperature measurements: -55 °C, +25 °C, and +125 °C.

4.3 Minimum and maximum cathode current

4.3.1 Minimum operating cathode current

The minimum operating cathode current ($I_{kmin.}$) is a combination of parameters (such as reference voltage, stability, noise, and process drift) that are taken over the ambient temperature range. For the RHF1009A, $I_{kmin.}$ is 60 μ A.

$I_{kmin.}$ is guaranteed over the ambient temperature range by [Equation 2](#).

$$\text{Equation 2: } V_k(I_k = 60 \mu\text{A}) \geq V_k(I_k = 100 \mu\text{A}, 25^\circ\text{C}) - 100 \mu\text{V}$$

4.3.2 Maximum operating cathode current ($I_{kmax.}$)

The maximum operating cathode current ($I_{kmax.}$) is limited by the output ballast current capabilities and process drift. For the RHF1009A, $I_{kmax.}$ is 12 mA.

$I_{kmax.}$ is guaranteed by the ΔV_k vs. ΔI_k parameter (see [Table 3](#)) and by [Equation 3](#) (at $T_{amb} = 25^\circ\text{C}$).

$$\text{Equation 3: } V_k(I_k = 12 \text{ mA}) \leq V_k(I_k = 100 \mu\text{A}, 25^\circ\text{C}) + 3 \text{ mV}$$

4.4 Capacitive load considerations

The RHF1009A can oscillate for a small I_k and no C_k . This is why we recommend a minimum capacitive load of 47 nF. The RHF1009A is designed to be stable with a capacitive load (C_k) over the cathode current range (60 μ A to 12 mA) and ambient temperature range (-55 °C to +125 °C).

If an oscillation amplitude less than 2 mVrms is acceptable, this device can be considered usable with any capacitive load given in [Figure 24: Recommended operating area](#).

[Figure 17](#) to [22](#) show spectral noise density measurements vs. frequency with a capacitive load of 100 nF and 1 μ F. With a capacitive load of 100 nF, all cathode currents are in the "Recommended Area" of [Figure 24](#) and there is no noise peak in the measured spectral noise density. With a capacitive load of 1 μ F, the 60 μ A and 100 μ A cathode currents are above C_k max in the "Not Recommended Area" of [Figure 24](#) and there is a noise peak in the measured spectral noise density for these I_k . For example, with a capacitive load of 1 μ F and $I_k = 60 \mu\text{A}$, there is a noise peak at about 5000 Hz. For the reverse breakdown voltage (V_k), this peaking corresponds to a micro-oscillation, with jitter, centered at 5000 Hz.

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

5.1 Ceramic Flat-10 package information

Figure 26. Ceramic Flat-10 package outline

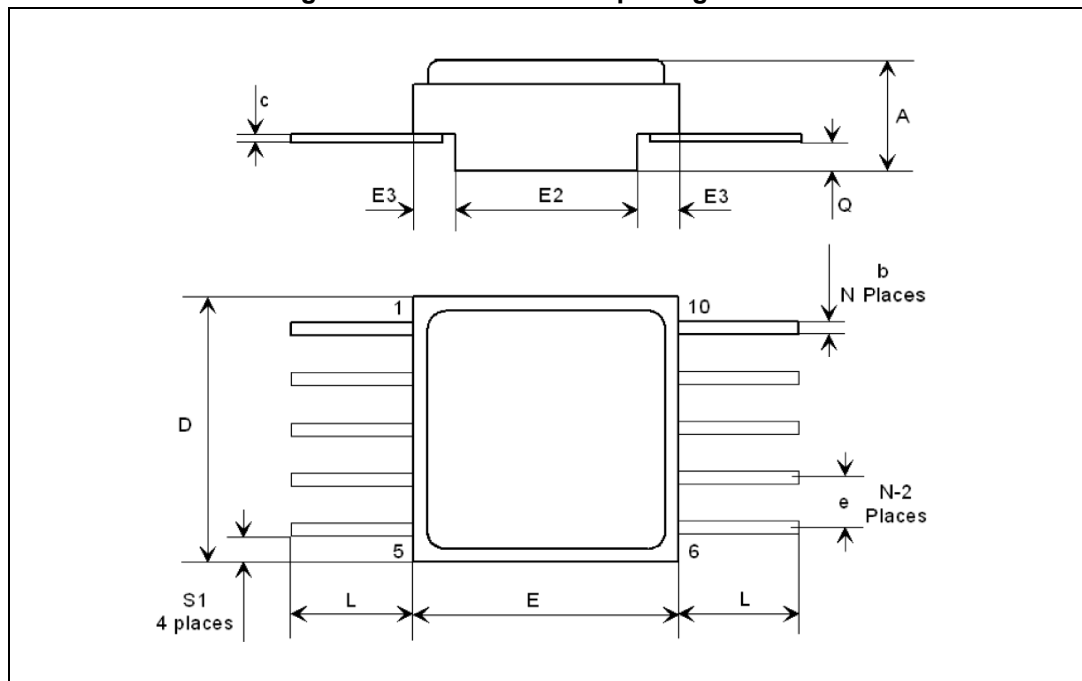


Table 5. Ceramic Flat-10 mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.26	2.44	2.62	0.089	0.096	0.103
b	0.38	0.43	0.48	0.015	0.017	0.019
c	0.102	0.127	0.152	0.004	0.005	0.006
D	6.35	6.48	6.60	0.250	0.255	0.260
E	6.35	6.48	6.60	0.250	0.255	0.260
E2	4.32	4.45	4.58	0.170	0.175	0.180
E3	0.88	1.01	1.14	0.035	0.040	0.045
e		1.27			0.050	
L	6.35		9.40	0.250		0.370
Q	0.66	0.79	0.92	0.026	0.031	0.036
S1	0.16	0.485	0.81	0.006	0.019	0.032
N	10			10		

Note: The upper metallic lid is not electrically connected to any pins, nor to the IC die inside the package.

6 Ordering information

Table 6. Order code

Order code	SMD ⁽¹⁾	Qualification level	Package	Lead finish	Marking ⁽²⁾	Packing
RHF1009AK1	-	Engineering Model	Flat-10	Gold	RHF1009AK1	Conductive strip pack
RHF1009AK01V	5962F14222	QML-V Flight		Gold	5962F1422201VXC	
RHF1009AK02V	5962F14222	QML-V Flight		Solder Dip	5962F1422201VXA	

1. Standard micro circuit drawing.

2. Specific marking only. Complete marking includes the following:

- ST logo
- Date code (date the package was sealed) in YYWWA (year, week, and lot index of week)
- Country of origin (FR = France)

7 Other information

7.1 Date code

The date code (date the package was sealed) is structured as follows:

- Engineering model: 3yywwz
- Flight model: yywwz

Where: yy = last two digits of the year, ww = week digits, z = lot index of the week

7.2 Product documentation

Each product shipment includes a set of associated documentation within the shipment box. This documentation depends on the quality level of the products, as detailed in the table below.

The certificate of conformance is provided on paper whatever the quality level. For QML parts, complete documentation, including the certificate of conformance, is provided on a CDROM.

Table 7. Product documentation

Quality level	Item
Engineering model	Certificate of conformance including: <ul style="list-style-type: none"> • Customer name • Customer purchase order number • ST sales order number and item • ST part number • Quantity delivered • Date code • Reference to ST datasheet • Reference to TN1181 on engineering models • ST Rennes assembly lot ID
QML-V Flight	Certificate of conformance including: <ul style="list-style-type: none"> • Customer name • Customer purchase order number • ST sales order number and item • ST part number • Quantity delivered • Date code • Serial numbers • Group C reference • Group D reference • Reference to the applicable SMD • ST Rennes assembly lot ID
	Quality control inspection (groups A, B, C, D, E)
	Screening electrical data in/out summary
	Precap report
	PIND (particle impact noise detection) test
	SEM (scanning electronic microscope) inspection report
	X-ray plates

8 Revision history

Table 8. Document revision history

Date	Revision	Changes
18-Jun-2014	1	Initial release
08-Jul-2015	2	Features: updated Vref. accuracy Table 3: Operating conditions: modified VKA Corrected Figure 20: Spectral noise density vs. freq. at +25 °C, Ck = 1 μ F and Figure 21: Spectral noise density vs. freq. at -55 °C, Ck = 100 nF. Added Figure 23: Low freq. spectral noise density vs. freq. Ck = 100 nF to 1 μ F, Ik = 60 μ A to 10 mA. Changed layout of Figure 24: Recommended operating area
09-Apr-2018	3	Updated the Description, Table 1: Device summary in cover page, Table 7: Order code and Table 8: Product documentation.
17-Nov-2023	4	Updated Section 4.4: Capacitive load considerations.
28-Jan-2025	5	Updated figure and features on the cover page, Section 6: Ordering information and Section 7: Other information .
12-Sep-2025	6	Added pin connections figure and new SMD: 5962F14222 feature on the cover page.

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